

IN THE CLAIMS:

1. (Currently Amended) A semiconductor integrated circuit device comprising:

a plurality of external signal input/output circuits;

a plurality of internal circuits arranged internally in a circuit forming region, said internal circuits having different power lines;

an inter-circuit signal wire arranged to interconnect said internal circuits, wherein said inter-circuit signal wire is not directly connected to said external signal input/output circuits [an input circuit or an output circuit];

an active element in a first connection configuration connected to said inter-circuit signal wire; and

a plurality of other active elements in a second connection configuration including elements of an identical [~~or similar~~] structure to said [an] active element in the [a] first connection configuration [~~connected to said inter-circuit signal wire~~],

 said plurality of active elements in the [said] second connection configuration being arranged adjacent to said active element in the first connection configuration to sandwich or surround said active element in the first connection configuration,

gates of said plurality of active elements in the [said] second connection configuration being connected only to power lines of said internal circuits associated therewith [~~and being isolated from signal wires other than said inter-circuit signal wire~~].

2. (Previously Amended) A semiconductor integrated circuit device according to claim 1, wherein each of said internal circuits includes a plurality of basic cells regularly arranged in repetition, and said active element in the first connection configuration and said plurality of active elements in the second connection configuration are allocated to some of said basic cells.

3. (Original) A semiconductor integrated circuit device according to claim 1, further comprising a substrate formed in a single chip, and said circuit forming region is allocated to one surface of said substrate.

4. (Cancelled)

5. (Currently Amended) A semiconductor integrated circuit device comprising:

a plurality of external signal input/output circuits;

a plurality of internal circuits arranged internally in a circuit forming region, said internal circuits having different power lines;

an inter-circuit signal wire arranged to interconnect said internal circuits, wherein said inter-circuit signal wire is not directly connected to said external signal input/output circuits [an input circuit or an output circuit];

an active element in a first connection configuration connected to said inter-circuit signal wire; and

another [an] active element in a second connection configuration arranged adjacent to
said [an] active element in the [a] first connection configuration [~~connected to said inter-circuit
signal-wire~~], including

an element of an identical [~~or similar~~] structure to said active element in
the first connection configuration,

gates of said active element in the [a] second connection configuration
being connected only to power lines of said internal circuits associated therewith
[~~and being isolated from said inter-circuit signal-wire and other signal wires~~].

6. (Original) A semiconductor integrated circuit device according to claim 5, wherein a plurality of said active elements in the second connection configuration are arranged to sandwich or surround said active element in the first connection configuration.

7. (Previously Amended) A semiconductor integrated circuit device according to claim 5, wherein each of said internal circuits includes a plurality of basic cells regularly arranged in repetition, and said active element in the first connection configuration and said plurality of active elements in the second connection configuration are allocated to some of said basic cells.

8. (Original) A semiconductor integrated circuit device according to claim 5, further comprising a substrate formed in a single chip, and said circuit forming region is allocated to one surface of said substrate.

9. (Cancelled)

10. (Currently Amended) A semiconductor integrated circuit device according to claim 5, further comprising an active element in a third connection configuration, arranged adjacent to said active element in the first connection configuration and including an element of an identical [or similar] structure to said active element in the first connection configuration, gates of said active element in the third connection configuration being connected to a power line of an internal circuit associated therewith and said inter-circuit signal wire[and being isolated from other signal lines].

11. (Original) A semiconductor integrated circuit device according to claim 10, wherein a plurality of said active elements in the third connection configuration are arranged to sandwich or surround said active element in the first connection configuration.

12-14. (Withdrawn)

15. (Previously Amended) A semiconductor integrated circuit device according to claim 10, wherein:

a plurality of said inter-circuit signal wires having different communication directions from each other are arranged to interconnect a pair of internal circuits;

said active element in the second connection configuration and said active element in the third connection configuration are arranged adjacent to said active element in the first connection configuration on a reception side of said inter-circuit signal wire in one of said pair of internal circuits; and

 said active elements in the third connection configuration are arranged independent of said active element in the second connection configuration, near said active element in the first connection configuration on a reception side of said inter-circuit signal wire in the other one of said pair of internal circuits.

16. (Previously Amended) A semiconductor integrated circuit device according to claim 15, wherein said active elements in the second connection configuration and said active elements in the third connection configuration are arranged to sandwich or surround said active element in the first connection configuration.

17-45. (Withdrawn)